

## COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Tao, Su

Date: Jun 23 2003

Sole or First Joint Inventor: Tao, Su

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 72-2, Tsungshih Hsin-tsun, Tsoying Chu, Kaohsiung, Taiwan, R.O.C.

Signature: Kuang Lin Lo

Date: Jun 23 2003

Second Joint Inventor (if any): Kuang-Lin Lo

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 50, Shen-Nung St., Jiou-Chiu Tsuen, Ta-Shu Shiang, Kaoshiung Hsien, Taiwan, R.O.C.

Signature: Tsung Sheng Lee

Date: Jun 23 2003

Third Joint Inventor (if any): Tsung-Sheng Lee

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 23, Liao-Ning I St., Kaoshiung, Taiwan, R.O.C.

Signature: Yaw Yuh Yang

Date: Jun 23 2003

Fourth Joint Inventor (if any): Yaw-Yuh Yang

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: 5F, No. 7, Alley 21, Lane 399, Sec. 3, Chunghua E Rd., Tainan, Taiwan, R.O.C.

Signature: Yuan-Kai Tao

Date: Jun 23 2003

Fifth Joint Inventor (if any): Yuan-Kai Tao

Citizenship: Taiwan, R.O.C.

Residence and Post Office Address: No. 1-1, Lane 98, Hua-Shang Rd., Chu-Hu Tsuen, Lu-Chu Shiang, Kaohsiung Hsien, Taiwan, R.O.C.

## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

### CHIP PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME

the specification of which

  X   is attached hereto.

       was filed on                                 

as Application Serial No.                                  and was amended on                                 .

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s):

Number	Country	Date Filed(yyyy/mm/dd)	Yes	No
91137974	Taiwan, R.O.C.	2002/12/31	X	

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

**Belinda Lee** (Reg. No. 46,863)  
**Jiawei Huang** (Reg. No. 43,330)  
**Charles C.H. Wu** (Reg. No. 39,081)

---

SEND CORRESPONDENCE TO:

DIRECT TELEPHONE CALLS TO:  
(Name and telephone number)

JIANQ CHYUN Intellectual Property Office  
7F.-1, No. 100, Roosevelt Rd., Sec. 2,  
Taipei 100, Taiwan, R.O.C.  
TEL: 886-2-2369 2800  
FAX: 886-2-2369 7233

**Belinda Lee**